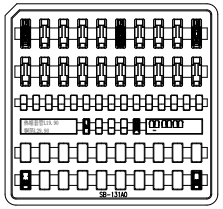
HSF

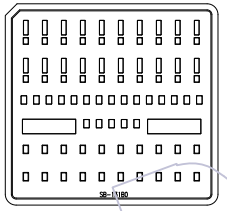
产品放置示意图详情见附页



No. 1

产品装入真空盒内,20SET/Tray

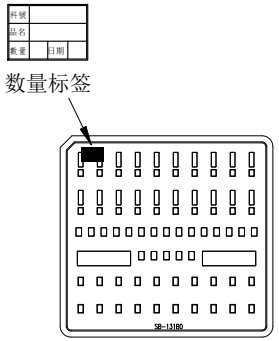
真空盒底规格:SB-131A0(280*265*15.0mm)



No. 2

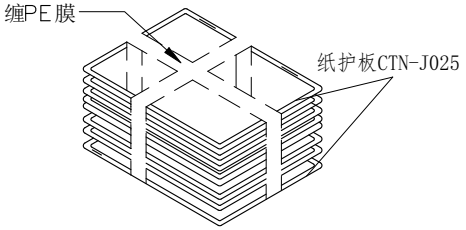
盖上盒盖

真空盒盖规格:SB-131B0(280*265*15.0mm)



No. 3

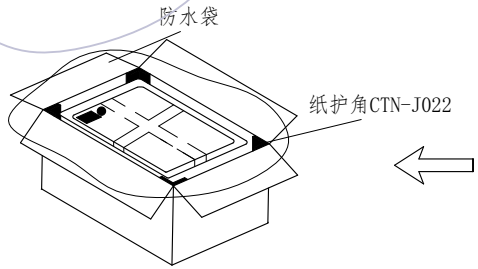
贴标签于真空盒左上角



No. 4

20盒为一扎,上下各放一块纸护板

再用PE膜缠绕成十字形



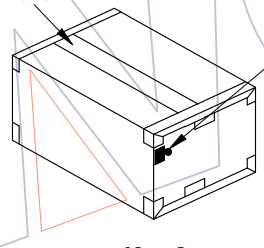
No. 5

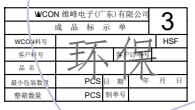
纸箱内需套防水袋，再将真空盒装入纸箱

(1扎/箱，400SET/箱)加一包干燥剂后封口，

四周各放置一个纸护角CTN-J022

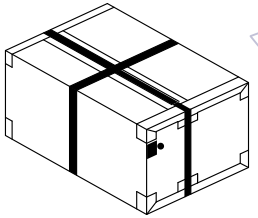
纸箱规格:CTN-74(30.5*30*33.5cm)





贴外箱标签及ROHS标签

ROHS



No. 7

打包装带

No. 6

封箱及贴标签于纸箱侧面的左上角

说明:

1. 产品如图所示型态放入真空盒
2. 注意各标签样式.位置及方向的一致性;
3. 打外箱包装带时需注意，打为十字型.

变更记事											
					零件图		颜色 COLOR		SCALE	fit	WCON ELECTRONICS (GUANGDONG) CO.,LTD
					X.	±0.50	材质 MATERIAL		UNIT	mm	
					X.X	±0.20					
					X.XX	±0.10	设计 DESING	苏 珊 2022/07/29	SIZE	A4	
					X.XXX	±0.05					
A0	2022/07/29	NEW			Angle		审核 CHECK		SHEET	1/2	料号 PART NO. 6362-08MXISXMCBAX 6362-08MXHSXMCBA1&2
					X.	± 2°	核准 APPROVE				
版次 REV	日期 DATE	变更说明 MODIFICATION DESCRIPTION	变更 CHANGE	核准 APPROVE	DIM	TOL			PROJ.		品名 TITLE: 1.27mm Micro I/O公头SOLDER TYPE 8P组件 1.27mm Micro I/O公头IDC TYPE 8P组件 包装规范